



Qualcomm Technologies, Inc.

Qualcomm[®] Robotics RB3 Platform

Machine Communication Mezzanine Specifications

Rev. A

February 15, 2019

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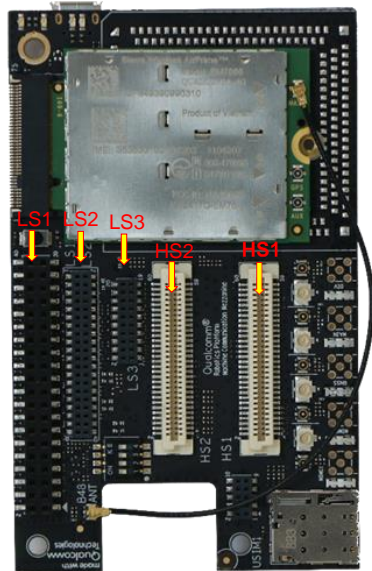
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Revision history

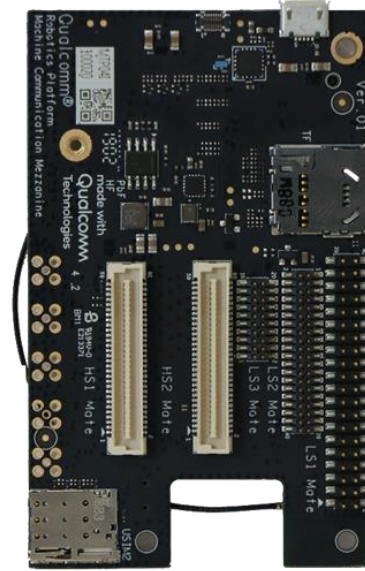
Revision	Date	Description
A	February 2019	Initial release

Machine Communication Mezzanine development board

The Machine Communication Mezzanine development board is designed to connect the cellular networks, adopts Sierra Wireless EM7565 Module which offers global 4G coverage, CBRS for private LTE networks, unprecedented LTE speeds, bandwidth, and network performance on the M.2 form factor. A built in Global Positioning System (GPS) device adds location and navigation to your application.



Top view



Back view

Technical specifications

Component	Description
Expansion interfaces	Expansion connectors: <ul style="list-style-type: none"> ▪ HS1:1 x 60 pin High-Speed connector (4L-MIPI DSI, USB 2.0 x2, I2C x2, 2L+4L-MIPI CSI, SDIO) ▪ HS2:1 x 60 pin High-Speed connector (4L-MIPI CSI x 2, SSC SPI, PCIe 3.0, USB 3.0 x1, GPIO x 9) ▪ LS1:1x 96boards 40 pin Low-Speed connector (UART x 2, SPI, I2S, I2C x2, GPIO x 12, DC power) ▪ LS2:1 x 96boards 40 pin low-speed connector (headset, stereo speaker, DMIC I/F x 3, CAN, I2S, GPIO x 7, PWM x 2, ADC x 2) ▪ LS3:1 x 96boards 20 pin Low-Speed connector (SSC SPI x 3, SSC I2C, sensor interrupt x 5)
Other Interfaces	<ul style="list-style-type: none"> ▪ 2 x USIM ▪ 1 x Micro B Debug for LTE ▪ 1 x B48 band antenna on board ▪ 1 x GNSS antenna connector ▪ 1 x main antenna connector ▪ 1 x div antenna connector ▪ 2 x MIMO antenna connectors ▪ 1 x M.2 interface
Cellular components	<ul style="list-style-type: none"> ▪ 1 x Sierra Wireless EM7565 M.2 Module ▪ 2 x 100mm coax cables ▪ 2 x 50mm coax cables ▪ 2 x Taoglas FXUB66 antennas
Size	<ul style="list-style-type: none"> ▪ 85 mm x 54 mm meeting 96Boards Consumer Edition Standard form dimensions specifications